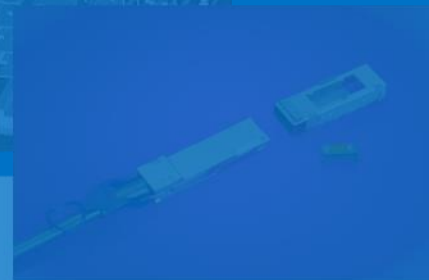
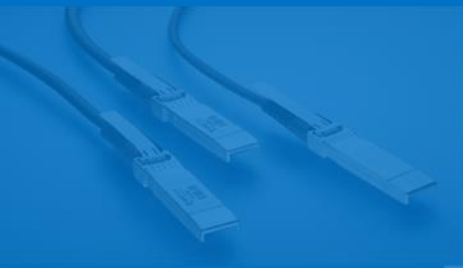


Electrical Interface Update

EA Meeting / Brocade Center
15 Oct 2014 Version r2



Opening

This is the personal view of Joel Goergen and not the view of IEEE P802.3bs. Joel Goergen makes no attempt to speak on behalf of the task force in any manor.

Please note the incredible work being done at this URL - <http://www.ieee802.org/3/bs/public/adhoc/index.shtml>

The Process Steps

The following simplified process steps are used to build consensus:

- Defining / Discussing Reach
 - System Architecture
 - **Channel Loss**
 - **Modulation**
 - Equalization
 - Error Correction
 - Power
- We Are Here**

From Sept 2014 Unapproved Minutes

Motion 4 (as modified by motion #5):

Move to adopt 16 x 25Gb/s and 8 x 50Gb/s as the basis for the lane rates for any optional C2C and C2M electrical interfaces

- - M: J. Goergen
- - S: V. Parthasarathy
- - Technical ($\geq 75\%$),
- - Y:102 ,N:0 ,A:4

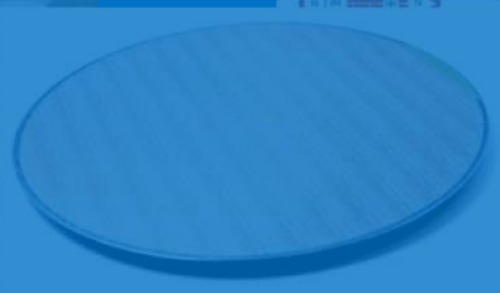
Motion #6:

Move to adopt the P802.3bm C2C and C2M specifications with current values (except that the BER requirement is TBD) as a baseline draft for the 16 x 25Gb/s electrical interfaces

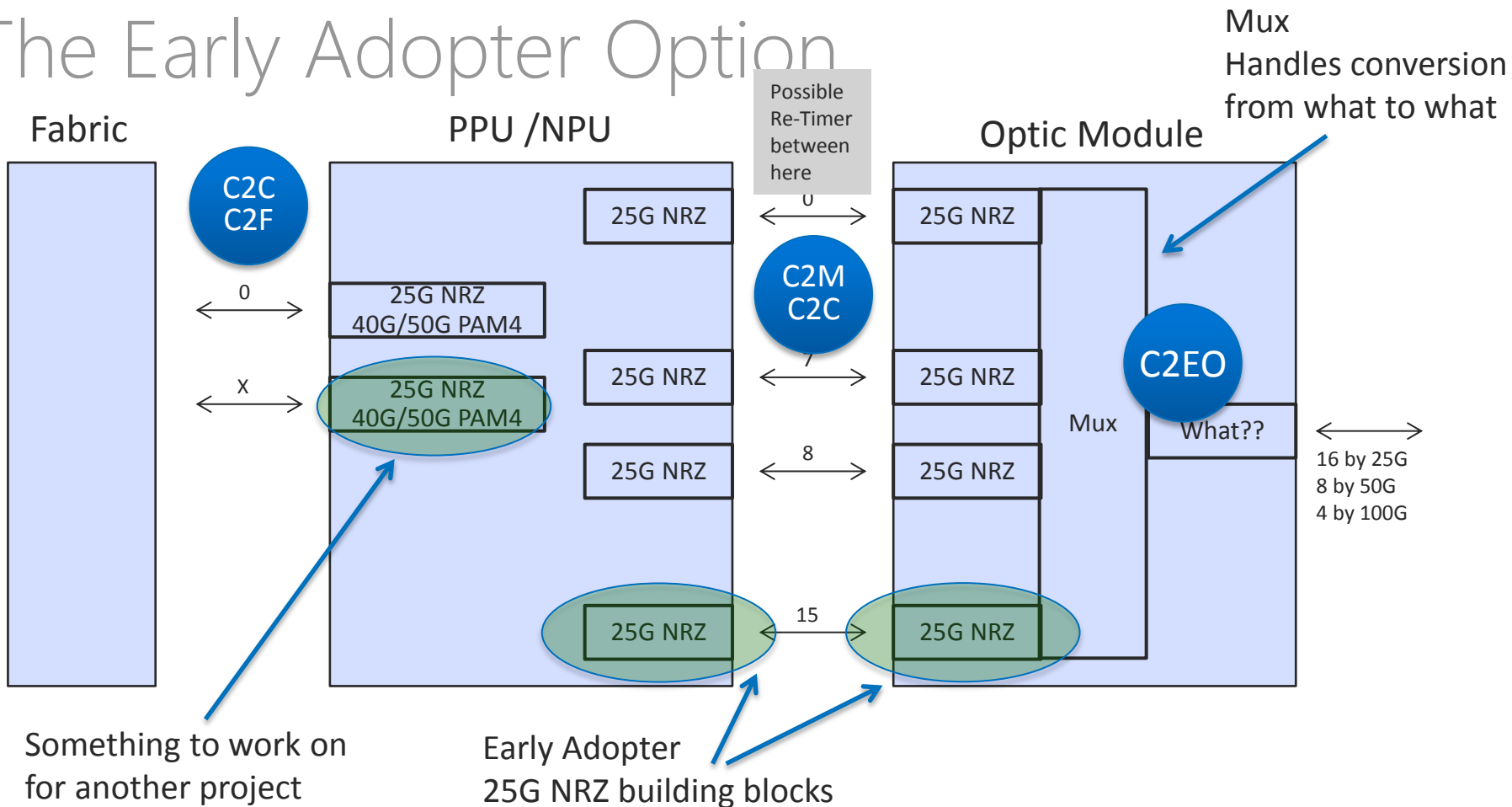
- - M: J. Goergen
- - S: V. Parthasarathy
- - Technical ($\geq 75\%$),
- - Y:78 ,N:0 ,A:18

System Architectures

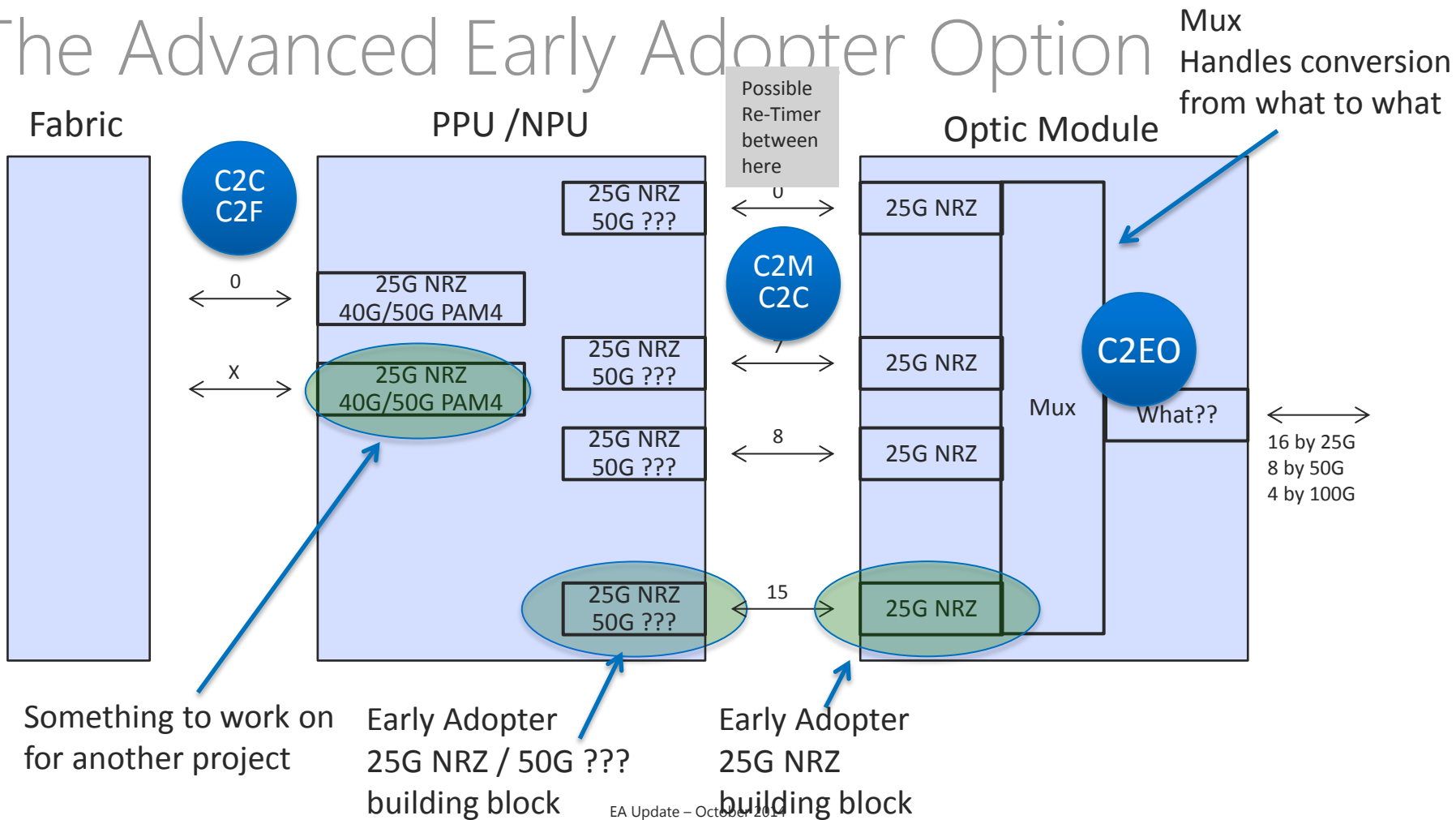
System building blocks at a high level



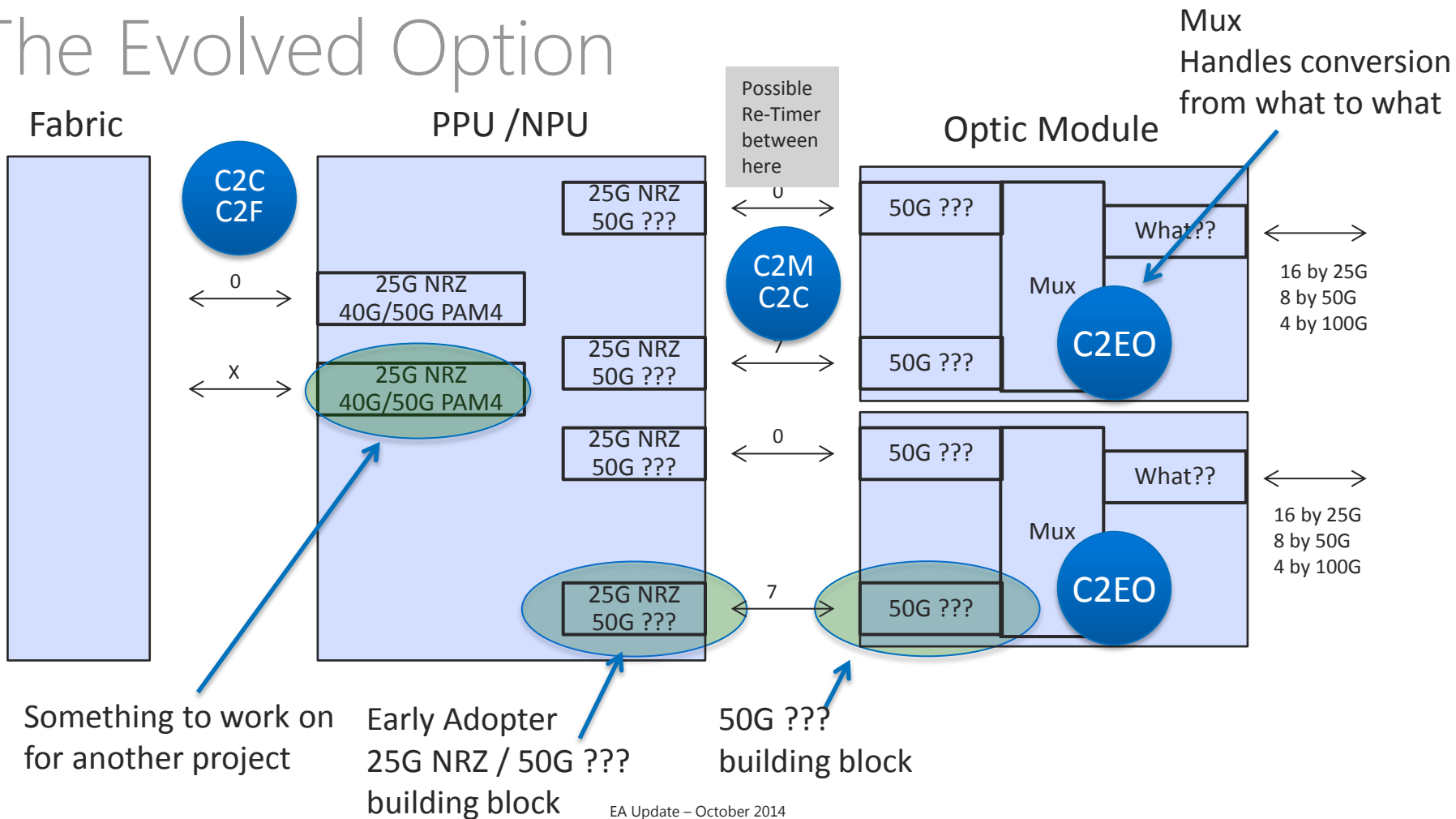
The Early Adopter Option



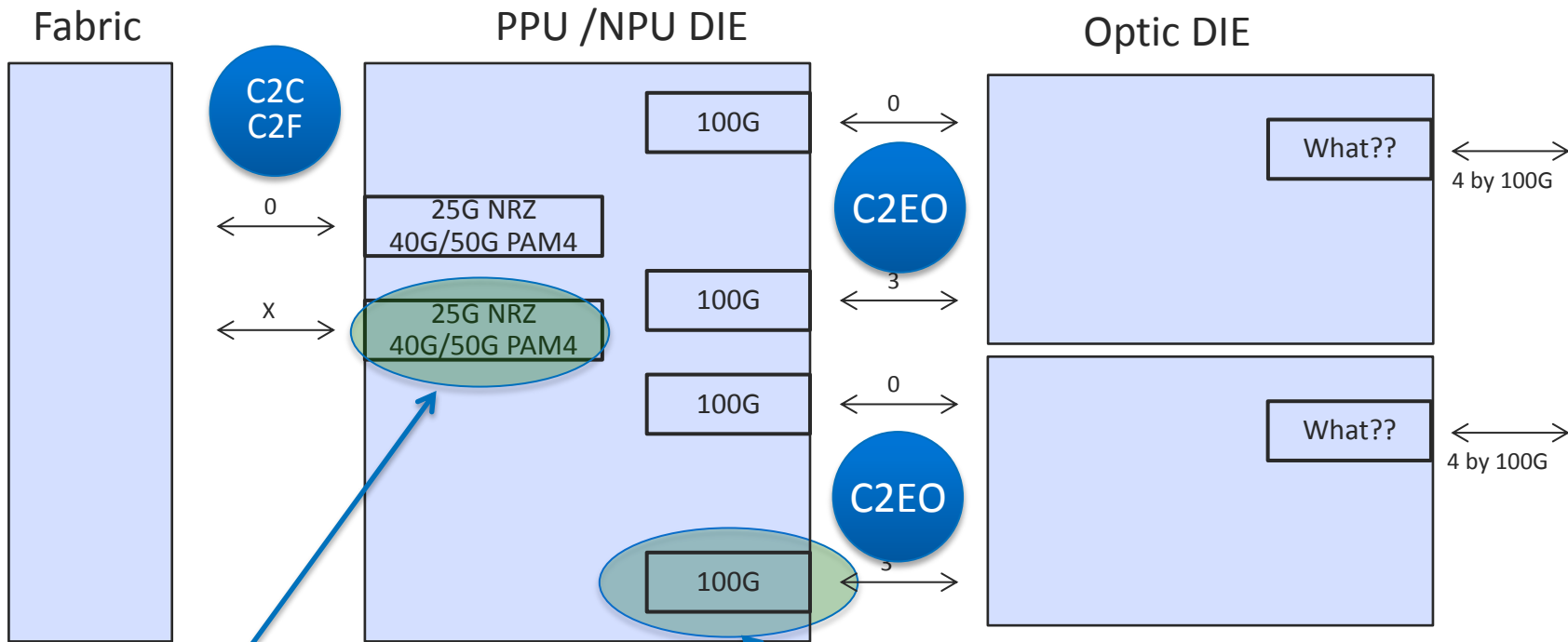
The Advanced Early Adopter Option



The Evolved Option



The Maybe-Some-day Option



Something to work on
for another project




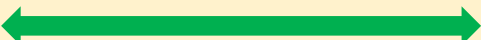
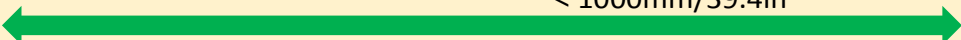
100G "what"
building block

Reach and Modulation

Looking at the 5 basic reach definitions talked about most
How to cover reach with the best coverage of SERDES cores







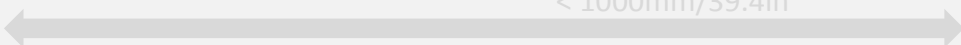
Length, Loss & Applications

		IL	
	< 10mm/0.4in	USR	1.5dB@14GHz 3dB@28GHz Bump-to-bump Inside MCM or 3D Stack
	< 50mm/2.0in	XSR C2EO	4dB@14GHz 8dB@28GHz Ball-to-ball Across PCB
	< 200mm/7.9in	VSR C2M	10dB@14GHz 20dB@28GHz Ball-to-ball
	< 500mm/19.7in	MR C2C	20dB@14GHz 40dB@28GHz Ball-to-ball
	< 1000mm/39.4in	LR C2F	35dB@14GHz Ball-to-ball

Length, Loss & Applications:

Today a single 25GB/s SERDES core can cover all these ranges

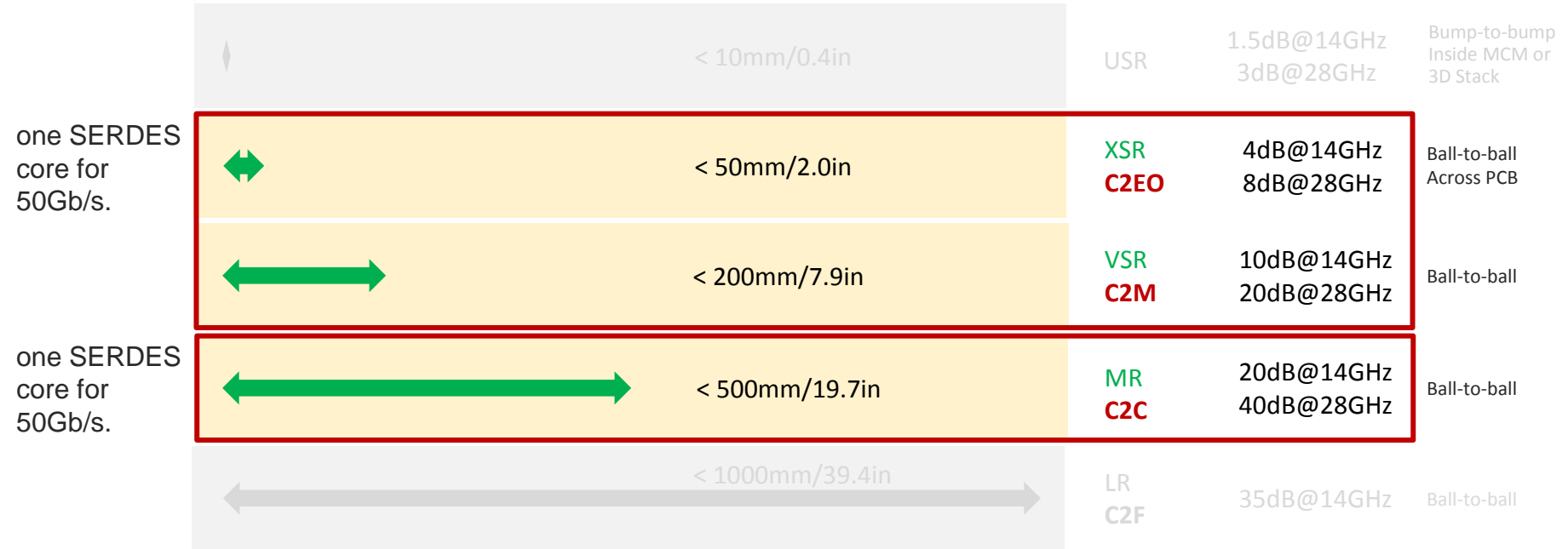
IL

		< 10mm/0.4in	USR	1.5dB@14GHz 3dB@28GHz	Bump-to-bump Inside MCM or 3D Stack
These ranges can be easily covered with one SERDES core today for 25Gb/s.		< 50mm/2.0in	XSR C2EO	4dB@14GHz 8dB@28GHz	Ball-to-ball Across PCB
		< 200mm/7.9in	VSR C2M	10dB@14GHz 20dB@28GHz	Ball-to-ball
		< 500mm/19.7in	MR C2C	20dB@14GHz 40dB@28GHz	Ball-to-ball
		< 1000mm/39.4in	LR C2F	35dB@14GHz	Ball-to-ball

Length, Loss & Applications: Grouping (Perspective 1)

How does a 50Gb/s SERDES core cover these ranges optimally?

IL





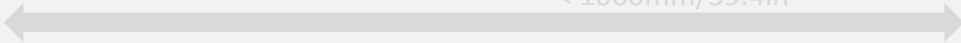


Unconfirmed but ... Under the impression from the group the cores should be compatible

Length, Loss & Applications: Grouping (Perspective 2)

How does a 50Gb/s SERDES core cover these ranges optimally?

IL





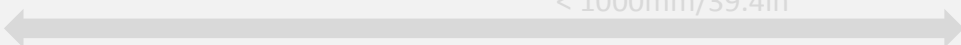
		< 10mm/0.4in	USR	1.5dB@14GHz 3dB@28GHz	Bump-to-bump Inside MCM or 3D Stack
one SERDES core for 50Gb/s.		< 50mm/2.0in	XSR C2EO	4dB@14GHz 8dB@28GHz	Ball-to-ball Across PCB
one SERDES core for 50Gb/s.		< 200mm/7.9in	VSR C2M	10dB@14GHz 20dB@28GHz	Ball-to-ball
		< 500mm/19.7in	MR C2C	20dB@14GHz 40dB@28GHz	Ball-to-ball
		< 1000mm/39.4in	LR C2F	35dB@14GHz	Ball-to-ball

Unconfirmed but ... Under the impression from the group the cores should be compatible

Length, Loss & Applications:

Future: a single 50GB/s SERDES core to cover all these ranges

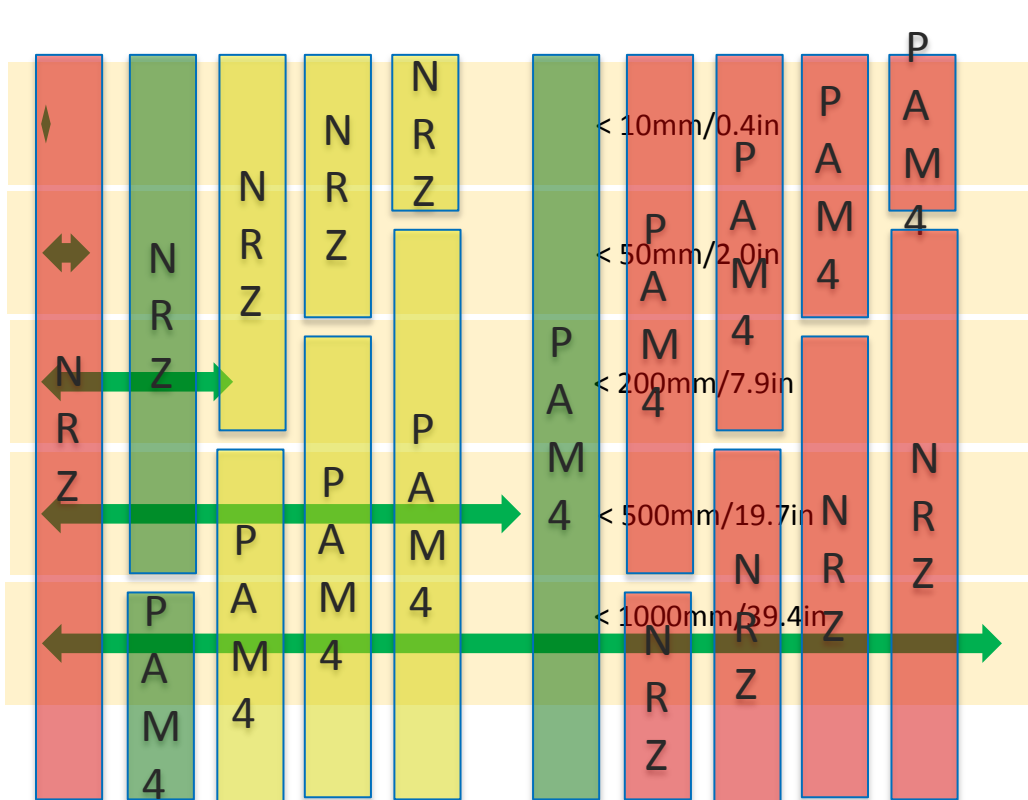
IL

		< 10mm/0.4in	USR	1.5dB@14GHz 3dB@28GHz	Bump-to-bump Inside MCM or 3D Stack
These ranges should be covered with one SERDES core in the future for 50Gb/s.		< 50mm/2.0in	XSR C2EO	4dB@14GHz 8dB@28GHz	Ball-to-ball Across PCB
		< 200mm/7.9in	VSR C2M	10dB@14GHz 20dB@28GHz	Ball-to-ball
		< 500mm/19.7in	MR C2C	20dB@14GHz 40dB@28GHz	Ball-to-ball
		< 1000mm/39.4in	LR C2F	35dB@14GHz	Ball-to-ball

I think the discussion comes down to this – even though we are only focused on C2C and C2M

S
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IL

USR	1.5dB@14GHz 3dB@28GHz	Bump-to-bump Inside MCM or 3D Stack
XSR C2EO	4dB@14GHz 8dB@28GHz	Ball-to-ball Across PCB
VSR C2M	10dB@14GHz 20dB@28GHz	Ball-to-ball
MR C2C	20dB@14GHz 40dB@28GHz	Ball-to-ball
LR C2F	35dB@14GHz	Ball-to-ball

Not Really Feasible

Compatibility Concerns

Feasible Technology – Min
Compatibility Concern

Confirming Action Item from Sept 2014 Meeting

Length, Loss & Application: Technologies for 50Gb/s

These Values are under discussion

Application	Length	Loss	Modulation	pJ/bit	DFE?	FEC?
C2EO (XSR)	< 2in	<4dB@14GHz	PAM-4	TBD	TBD	TBD
		<8dB@28GHz	NRZ	TBD	TBD	TBD
C2M (VSR)	2-8in	4-10dB@14GHz	PAM-4	TBD	TBD	TBD
		8-20dB@28GHz	NRZ	TBD	TBD	TBD
C2C (MR)	8-20in	10-20dB@14GHz	PAM-4	TBD	TBD	TBD
		20-40dB@28GHz	NRZ	TBD	TBD	TBD

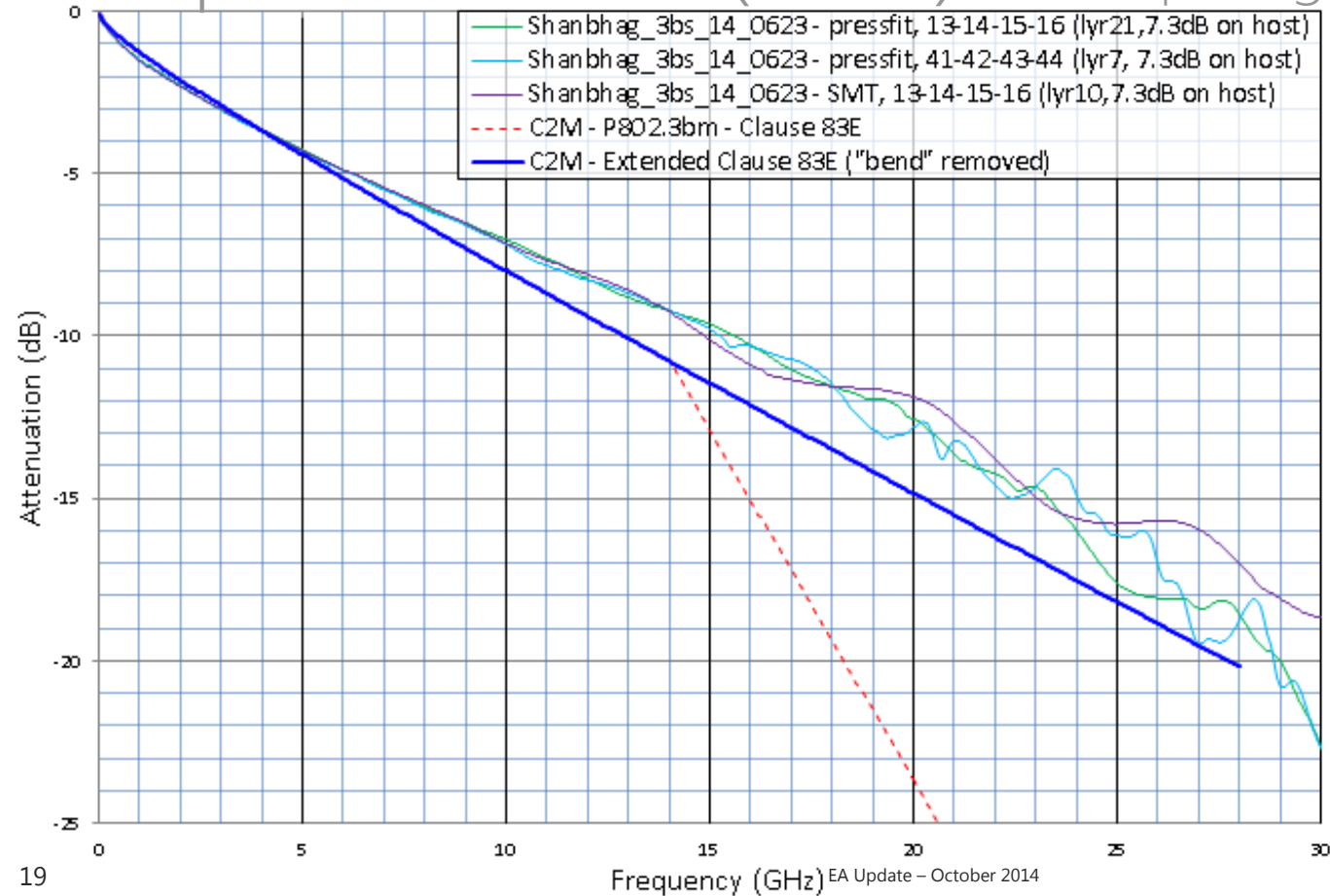
Knowing the reach definition allows us to begin understanding the next steps in the consensus building process

- System Architecture
- Channel Loss
- Modulation
- Equalization
- Error Correction
- Power

Sandy Limit Lines

Looking at some possible limit lines to guide channel definitions for modulation simulation

Chip-to-Module (C2M) – Comparing channel data



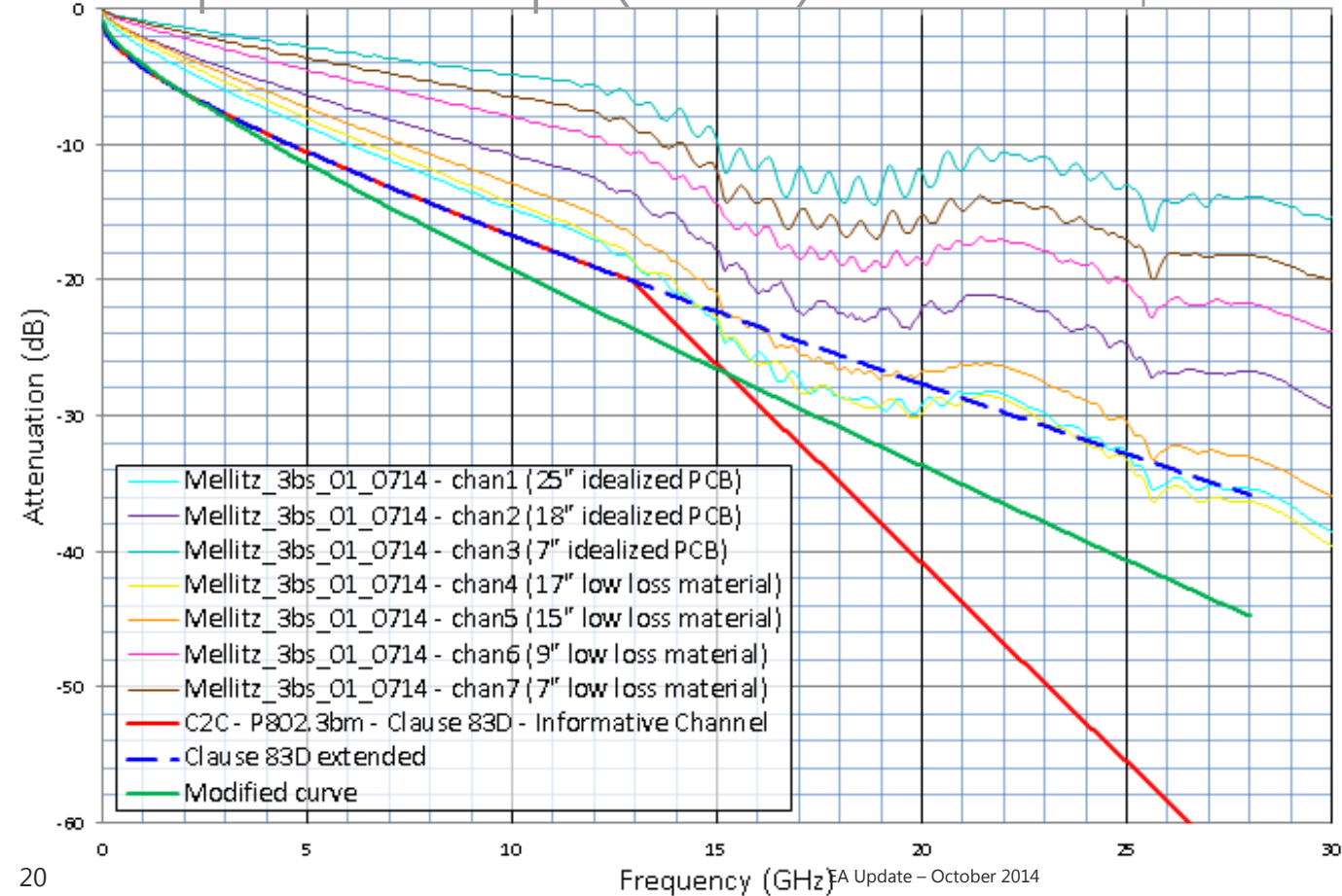
Notes:

← TE Channels developed using HFSS/ADS modeling tools.

← The 4" host trace is and should be supported at mid-loss materials by 100G standards... 7" is certainly seen in designs, but industries seem to recognize and adjust with material and design tradeoffs.

Propose: Use extended CAUI4 C2M-like channels for Modulation discussion/comparison

Chip-to-Chip (C2C) – Let's compare to channel data.



Notes:

← Channels are public on the .3bs webpage... all channels include connector and an 8% impedance variation from motherboard to daughtercard.

← Are these channels right to use for modulation discussion?

← Is ILD pessimistic for educated 50G channel design?

Sandy Line

Equations plotted for C2C and C2M

802.3bm draft – C2M equation (red curve)

$$Insertion_loss(f) \leq \left\{ \begin{array}{ll} 1.076(0.075 + 0.537\sqrt{f} + 0.566f) & 0.01 \leq f < 14 \\ 1.076(-18 + 2f) & 14 \leq f < 18.75 \end{array} \right\} \text{ (dB)} \quad (83E-1)$$

802.3bm draft – c2C equation (red curve) *although, standard uses COM as the normative spec, the following is offered as the informative “limit” line

$$Insertion_loss(f) \leq \left\{ \begin{array}{ll} 1.083 + 2.543\sqrt{f} + 0.761f & 0.01 \leq f < 12.89 \\ -17.851 + 2.936f & 12.89 \leq f < 25.78 \end{array} \right\} \text{ (dB)} \quad (83D-1)$$

C2M and C2C “extended curve” (blue curves)

Simply extend first portion of above curves for full frequency range; omit 14-18.75G and 12.89-25.78G equations, respectively.

Suggested/modified curve drawn in C2C (green curve)

$$0.9 + 2.1\sqrt{f} + 1.17f$$

Next Steps



Next Steps to Nov 2014 Proposals

- Use the C2C and C2M channels submitted to the P802.3bs and provide a modulation scheme.
- Reach consensus on which channel groupings (LR/MR-C2C/VSR-C2M/XSR/USR) make sense from power/performance tradeoffs based on simulations



Thank you!

From:

Vasu Parthasarathy
Beth Kochuparambil
Vivek Telang
Joel Goergen